

## NC7S02

### TinyLogic® HS 2-Input NOR Gate

#### General Description

The NC7S02 is a single 2-Input high performance CMOS NOR Gate. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad  $V_{CC}$  range. ESD protection diodes inherently guard both inputs and output with respect to the  $V_{CC}$  and GND rails. Three stages of gain between inputs and outputs assures high noise immunity and reduced sensitivity to input edge rate.

#### Features

- Space saving SOT23 or SC70 5-lead packages
- Ultra small MicroPak™ leadless package
- High Speed;  $t_{PD}$  3.5 ns typ
- Low Quiescent Power;  $I_{CC} < 1 \mu A$
- Balanced Output Drive; 2 mA  $I_{OL}$ , -2 mA  $I_{OH}$
- Broad  $V_{CC}$  Operating Range; 2V-6V
- Balanced Propagation Delays
- Specified for 3V operation

#### Ordering Code:

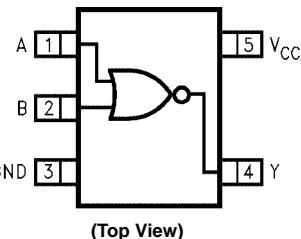
Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7S02M5X	MA05B	7S02	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7S02P5X	MAA05A	S02	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7S02L6X	MAC06A	E4	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

#### Logic Symbol

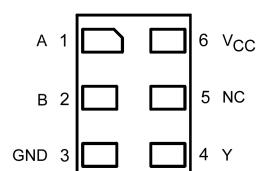


#### Connection Diagrams

Pin Assignments for SOT23 and SC70



Pad Assignments for MicroPak



#### Pin Descriptions

Pin Names	Description
A, B	Inputs
Y	Output
NC	No Connect

#### Function Table

$Y = \overline{A + B}$		
Inputs		Output
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	L

H = HIGH Logic Level  
L = LOW Logic Level

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<b>Absolute Maximum Ratings</b> <sup>(Note 1)</sup>							<b>Recommended Operating Conditions</b> <sup>(Note 2)</sup>	
Supply Voltage ( $V_{CC}$ )				-0.5V to +7.0V			Supply Voltage ( $V_{CC}$ )	2.0V to 6.0V
DC Input Diode Current ( $I_{IK}$ )							Input Voltage ( $V_{IN}$ )	0V to $V_{CC}$
@ $V_{IN} \leq -0.5V$				-20 mA			Output Voltage ( $V_{OUT}$ )	0V to $V_{CC}$
@ $V_{IN} \geq V_{CC} + 0.5V$				+20 mA			Operating Temperature ( $T_A$ )	-40°C to +85°C
DC Input Voltage ( $V_{IN}$ )				-0.5V to $V_{CC} + 0.5V$			Input Rise and Fall Time ( $t_r, t_f$ )	
DC Output Diode Current ( $I_{OK}$ )							$V_{CC} @ 2.0V$	0 to 1000 ns
@ $V_{OUT} < -0.5V$				-20 mA			$V_{CC} @ 3.0V$	0 to 750 ns
@ $V_{OUT} > V_{CC} + 0.5V$				+20 mA			$V_{CC} @ 4.5V$	0 to 500 ns
DC Output Voltage ( $V_{OUT}$ )				-0.5V to $V_{CC} + 0.5V$			$V_{CC} @ 6.0V$	0 to 400 ns
DC Output Source or Sink Current ( $I_{OUT}$ )				±12.5 mA			Thermal Resistance ( $\theta_{JA}$ )	
DC $V_{CC}$ or Ground Current per Output Pin ( $I_{CC}$ or $I_{GND}$ )				±25 mA			SOT23-5	300°C/W
Storage Temperature ( $T_{STG}$ )				-65°C to +150°C			SC70-5	425°C/W
Junction Temperature ( $T_J$ )				150°C				
Lead Temperature ( $T_L$ ) (Soldering, 10 seconds)				260°C				
Power Dissipation ( $P_D$ ) @ +85°C								
SOT23-5				200 mW				
SC70-5				150 mW				
<b>DC Electrical Characteristics</b>								
Symbol	Parameter	$V_{CC}$ (V)	$T_A = +25^\circ C$			Units	Conditions	
			Min	Typ	Max			Min
$V_{IH}$	HIGH Level Input Voltage	2.0 3.0-6.0	1.50 0.7 $V_{CC}$		1.50 0.7 $V_{CC}$	V		
$V_{IL}$	LOW Level Input Voltage	2.0 3.0-6.0		0.50 0.3 $V_{CC}$	0.50 0.3 $V_{CC}$	V		
$V_{OH}$	HIGH Level Output Voltage	2.0 3.0 4.5 6.0	1.90 2.90 4.40 5.90	2.0 3.0 4.5 6.0	1.90 2.90 4.40 5.90	V	$I_{OH} = -20 \mu A$ $V_{IN} = V_{IL}$	
		3.0 4.5 6.0	2.68 4.18 5.68	2.85 4.35 5.85	2.63 4.13 5.63	V	$V_{IN} = V_{IL}$ $I_{OH} = -1.3 mA$ $I_{OH} = -2 mA$ $I_{OH} = -2.6 mA$	
		2.0 3.0 4.5 6.0	0.0 0.0 0.0 0.1	0.10 0.10 0.10 0.26	0.10 0.10 0.10 0.33	V	$I_{OL} = 20 \mu A$ $V_{IN} = V_{IH}$	
		3.0 4.5 6.0	0.1 0.1 0.1	0.26 0.26 0.26	0.33 0.33 0.33	V	$V_{IN} = V_{IH}$ $I_{OL} = 1.3 mA$ $I_{OL} = 2 mA$ $I_{OL} = 2.6 mA$	
$I_{IN}$	Input Leakage Current	6.0		±0.1	±1.0	μA	$V_{IN} = V_{CC}, GND$	
$I_{CC}$	Quiescent Supply Current	6.0		1.0	10.0	μA	$V_{IN} = V_{CC}, GND$	

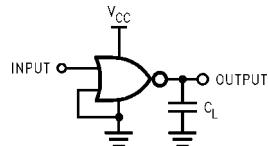
## AC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C			Units	Conditions	Figure Number
			Min	Typ	Max	Min	Typ	Max			
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	5.0	3.5	15			125		ns	C <sub>L</sub> = 15 pF	Figures 1, 3
		2.0	19	100			35			C <sub>L</sub> = 50 pF	
		3.0	10.5	27			25				
		4.5	7.5	20			21				
		6.0	6.5	17							
t <sub>TLH</sub> , t <sub>THL</sub>	Output Transition Time	5.0	3	10			155		ns	C <sub>L</sub> = 15 pF	Figures 1, 3
		2.0	25	125			45			C <sub>L</sub> = 50 pF	
		3.0	16	35			31				
		4.5	11	25			26				
		6.0	9	21							
C <sub>IN</sub>	Input Capacitance	Open	2	10		10		pF			
C <sub>PD</sub>	Power Dissipation Capacitance	5.0	6					pF	(Note 3)	Figure 2	

Note 3: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (See Figure 2.) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression:

$$I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC\text{static}})$$

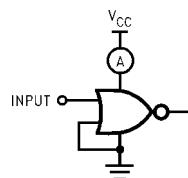
## AC Loading and Waveforms



C<sub>L</sub> includes load and stray capacitance

Input PRR = 1.0 MHz; t<sub>w</sub> = 500 ns

FIGURE 1. AC Test Circuit



Input = AC Waveform;

PRR = variable; Duty Cycle = 50%

FIGURE 2. I<sub>CCD</sub> Test Circuit

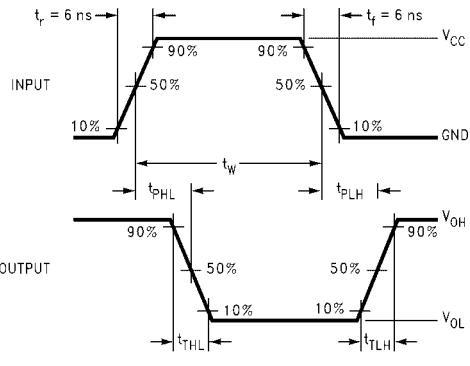


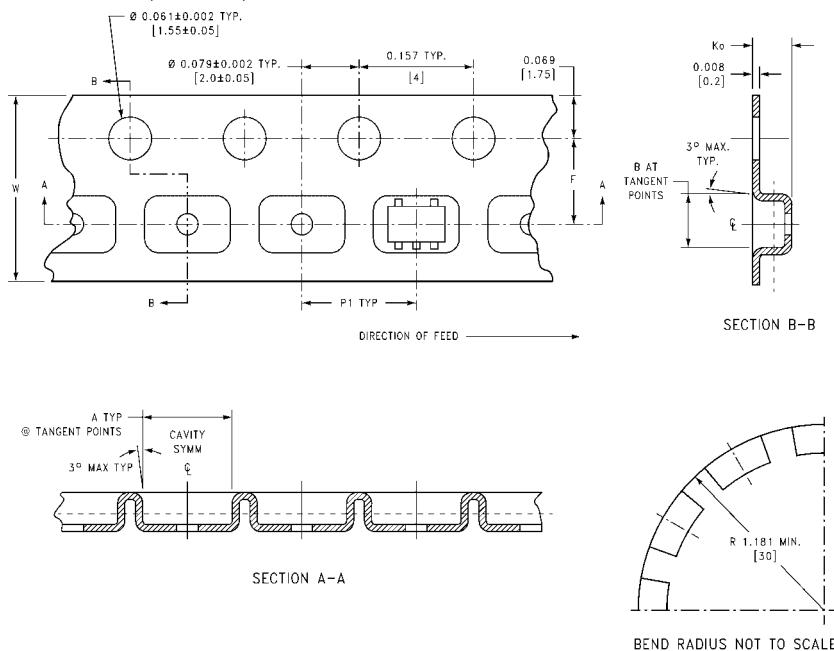
FIGURE 3. AC Waveforms

## Tape and Reel Specification

### TAPE FORMAT for SOT23 and SC70

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

### TAPE DIMENSIONS inches (millimeters)



Package	Tape Size	DIM A	DIM B	DIM F	DIM K <sub>o</sub>	DIM P1	DIM W
SC70-5	8 mm	0.093 (2.35)	0.096 (2.45)	$0.138 \pm 0.004$ (3.5 ± 0.10)	$0.053 \pm 0.004$ (1.35 ± 0.10)	0.157 (4)	$0.315 \pm 0.004$ (8 ± 0.1)
SOT23-5	8 mm	0.130 (3.3)	0.130 (3.3)	$0.138 \pm 0.002$ (3.5 ± 0.05)	$0.055 \pm 0.004$ (1.4 ± 0.11)	0.157 (4)	$0.315 \pm 0.012$ (8 ± 0.3)

**Tape and Reel Specification** (Continued)  
**TAPE FORMAT for MicroPak**

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

**SECTION A-A**  
SCALE:10X

**SECTION B-B**  
SCALE:10X

**REEL DIMENSIONS** inches (millimeters)

**DETAIL X**  
SCALE: 3X

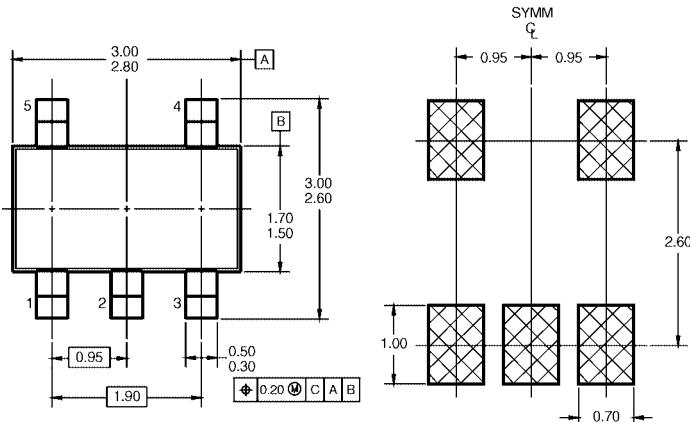
Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/-0.000 (8.40 + 1.50/-0.00)	0.567 (14.40)	W1 + 0.078/-0.039 (W1 + 2.00/-1.00)

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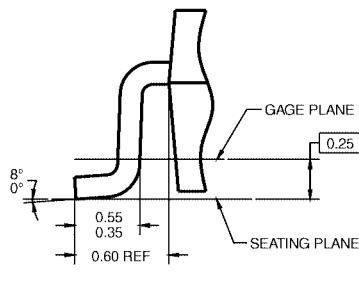
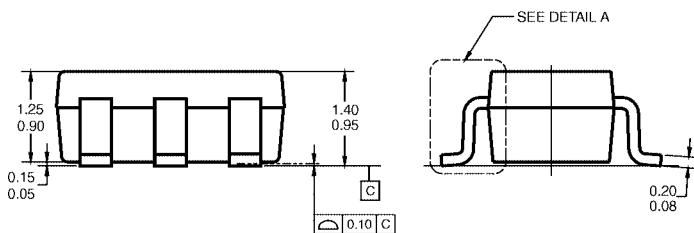
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**NC7S02**

**Physical Dimensions** inches (millimeters) unless otherwise noted



LAND PATTERN RECOMMENDATION



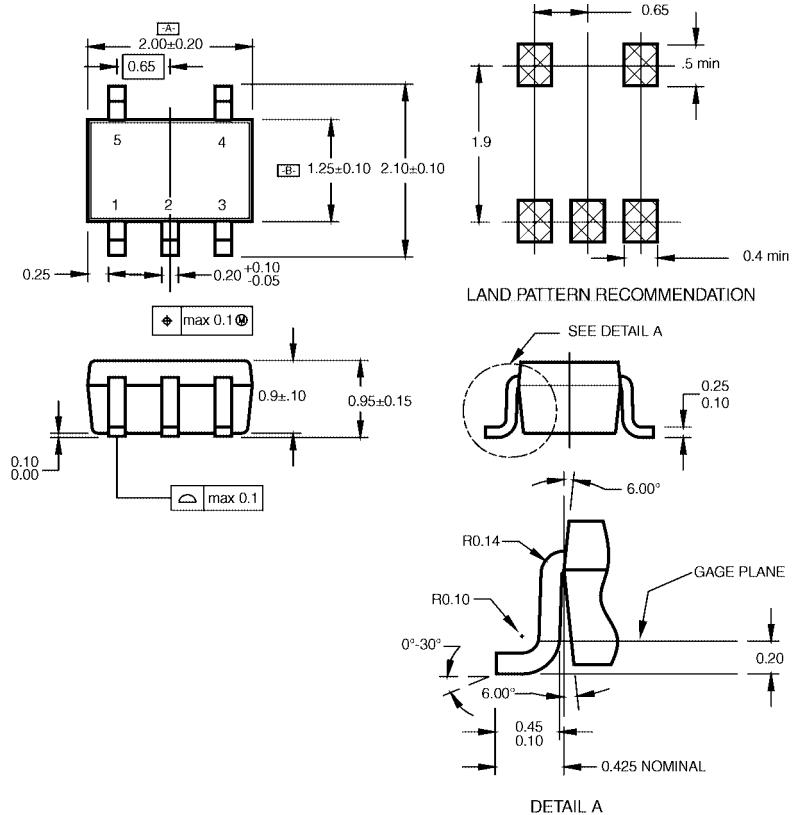
NOTES: UNLESS OTHERWISE SPECIFIED  
A) THIS PACKAGE CONFORMS TO JEDEC  
MO-178, ISSUE B, VARIATION AA,  
DATED JANUARY 1999.  
B) ALL DIMENSIONS ARE IN MILLIMETERS.

MA05BRevC

DETAIL A

**5-Lead SOT23, JEDEC MO-178, 1.6mm  
Package Number MA05B**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

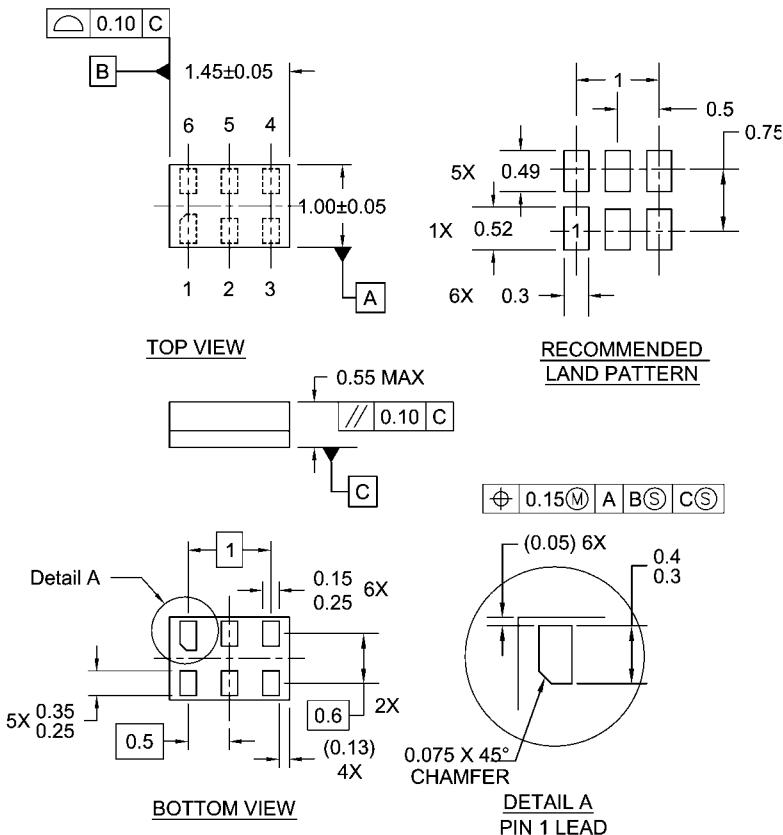


### NOTES:

- A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88A.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
- C. DIMENSIONS ARE IN MILLIMETERS.

MAA05ARevC

**5-Lead SC70, EIAJ SC-88a, 1.25mm Wide  
Package Number MAA05A**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

## Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

**6-Lead MicroPak, 1.0mm Wide  
Package Number MAC06A**

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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